# **DMC20501**

# Silicon NPN epitaxial planar type

For general amplification

#### ■ Features

- $\bullet$  High forward current transfer ratio  $h_{\text{FE}}$  with excellent linearity
- ullet Low collector-emitter saturation voltage  $V_{\text{CE(sat)}}$
- Halogen-free / RoHS compliant
   (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

## ■ Marking Symbol: B0

#### ■ Basic Part Number

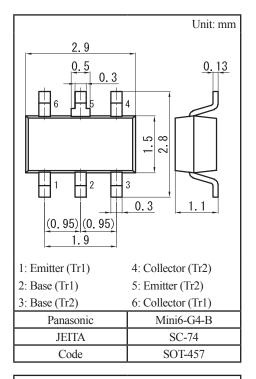
Dual DSC2001 (Individual)

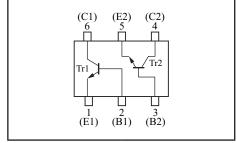
#### ■ Packaging

DMC205010R Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

### ■ Absolute Maximum Ratings $T_a = 25$ °C

|            | Parameter                             | Symbol           | Rating                      | Unit |
|------------|---------------------------------------|------------------|-----------------------------|------|
| Tr1<br>Tr2 | Collector-base voltage (Emitter open) | V <sub>CBO</sub> | 60                          | V    |
|            | Collector-emitter voltage (Base open) | V <sub>CEO</sub> | 50                          | V    |
|            | Emitter-base voltage (Collector open) | $V_{EBO}$        | 7                           | V    |
|            | Collector current                     | $I_{C}$          | 100                         | mA   |
|            | Peak collector current                | I <sub>CP</sub>  | 200                         | mA   |
| Overall    | Total power dissipation               | $P_{T}$          | 300                         | mW   |
|            | Junction temperature                  | T <sub>j</sub>   | 150                         | °C   |
|            | Operating ambient temperature         | T <sub>opr</sub> | T <sub>opr</sub> -40 to +85 |      |
|            | Storage temperature                   | T <sub>stg</sub> | -55 to +150                 | °C   |



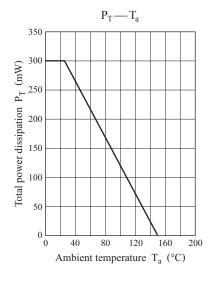


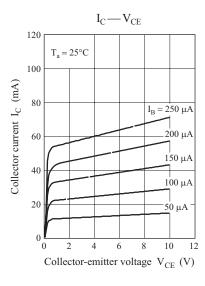
### ■ Electrical Characteristics $T_a = 25$ °C±3°C

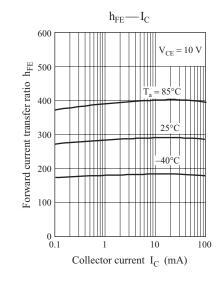
| Parameter  | Symbol                        | Conditions  | Min  | Тур  | Max | Unit |
|--|-------------------------------|---|------|------|-----|------|
| Collector-base voltage (Emitter open)                            | $V_{CBO}$                     | $I_{\rm C} = 10  \mu A, I_{\rm E} = 0$                | 60   |      |     | V    |
| Collector-emitter voltage (Base open)                            | V <sub>CEO</sub>              | $I_C = 2 \text{ mA}, I_B = 0$                         | 50   |      |     | V    |
| Emitter-base voltage (Collector open)                            | $V_{\rm EBO}$                 | $I_E = 10 \mu A, I_C = 0$                             | 7    |      |     | V    |
| Collector-base cutoff current (Emitter open)                     | $I_{CBO}$                     | $V_{CB} = 20 \text{ V}, I_{E} = 0$                    |      |      | 0.1 | μΑ   |
| Collector-emitter cutoff current (Base open)                     | $I_{CEO}$                     | $V_{CE} = 10 \text{ V}, I_{B} = 0$                    |      |      | 100 | μΑ   |
| Forward current transfer ratio                                   | $h_{FE}$                      | $V_{CE} = 10 \text{ V}, I_{C} = 2 \text{ mA}$         | 210  |      | 460 | _    |
| h <sub>FE</sub> ratio *1   | h <sub>FE</sub> (Small/Large) | $V_{CE} = 10 \text{ V}, I_{C} = 2 \text{ mA}$         | 0.50 | 0.99 |     | _    |
| Collector-emitter saturation voltage                             | V <sub>CE(sat)</sub>          | $I_C = 100 \text{ mA}, I_B = 10 \text{ mA}$           |      | 0.13 | 0.3 | V    |
| Transition frequency   | $f_T$                         | $V_{CE} = 10 \text{ V}, I_{C} = 2 \text{ mA}$         |      | 150  |     | MHz  |
| Collector output capacitance (Common base, input open circuited) | C <sub>ob</sub>               | $V_{CB} = 10 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$ |      | 1.5  |     | pF   |

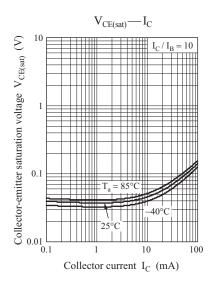
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

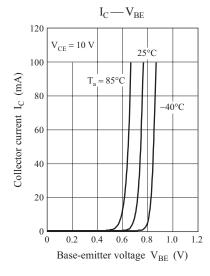
2. \*1: Ratio between 2 elements

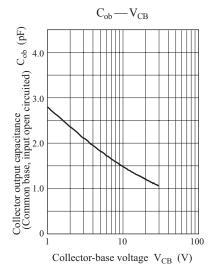


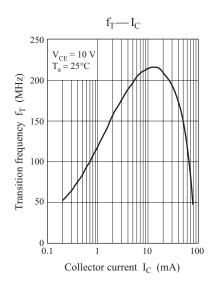








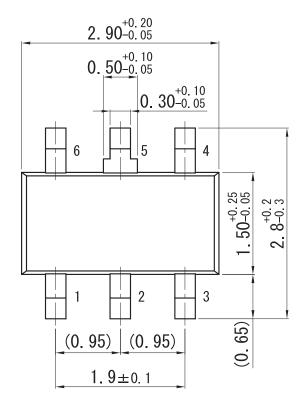


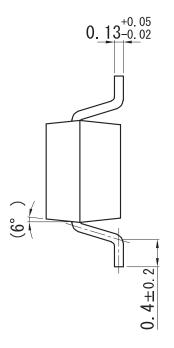


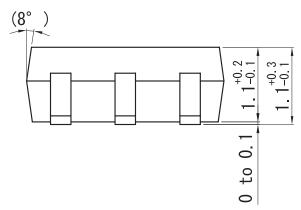
Ver. EED 2

Mini6-G4-B

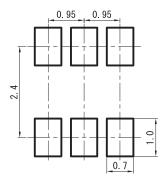
Unit: mm







# ■ Land Pattern (Reference) (Unit: mm)



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